JSCJ

MSDS Report

Report NO.: M000004000136

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC90P02
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.7585%
Lead Frame	Copper	7440-50-8	97.52%	35.2133%
	Iron	7439-89-6	2.35%	
	P	7723-14-0	0.08%	
	Plating Ag	7440-22-4	0.05%	
Epoxy	Silver Powder	7440-22-4	78.00%	1.0353%
	Epoxy Resin	9003-36-5	7.00%	
	Diluent A	3101-60-8	3.00%	
	Diluent B	Trade secret	2.00%	
	Diluent C	Trade secret	2.00%	
	Hardener A	Trade secret	2.00%	
	Hardener B	Trade secret	2.00%	
	Solvent	Trade secret	2.00%	
	Organic Peroxide	Trade secret	2.00%	
Aluminum Ribbon	Aluminum	7429-90-5	100.00%	2.4966%
Wire	Copper	7440-50-8	97.95%	
	Palladium	7440/5/3	1.80%	
	Gold	7440-57-5	0.25%	
Mold Compound	Silica	60676-86-0	82.00%	54.0173%
	Epoxy Resin	85954-11-6	10.00%	
	Phenol Resin	26834-02-6	7.50%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.99%	2.479%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.